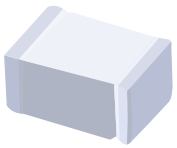
FEATURES

- Surface Mounting Design 4.5*3.2*2.7mm
- High Current Handling Capability 3000A @ 8/20 μs
- Low Capacitance and Insertion Loss
- Quick Response and Long Service Life
- Moisture sensitivity level：Level 1



4.5*3.2*2.7mm

Schematic Symbol

APPLICATION INFORMATION

- Communication equipment.
- Repeaters,Modems
- Telephone Interface,Line cards.
- Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free
c UL us	UL Certificated E505857

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	120-180	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ⩽ 700	V
	At 1kV/μs	Typical values of distribution ⩽ 600	V
Impulse Discharge Current 2)	8/20μs	3000	A
Insulation Resistance	DC=50V	⩾ 1	GΩ
Capacitance at 1MHz	V_{DC}=0.5V	⩽ 1.0	pF
Operating And Storage Temperature		-40-125	℃

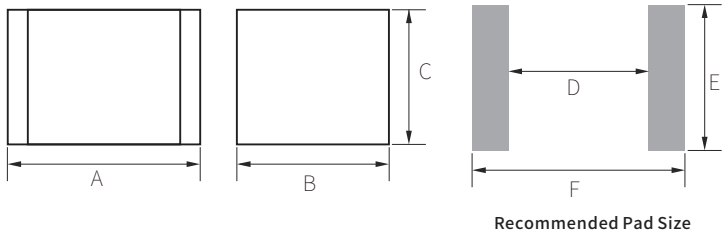
1) In ionized mode
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85℃ ; Time:2H
Low Temperature Storage Test	Temperature: -40℃ ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude：0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260±5℃; Time of dip soldering：10s, 1time

NOTE: Up-screen program can be specified by customer’s request via contacting Semiware service

DIMENSIONS AND RECOMMENDED SOLDERING PAD



Recommended Pad Size

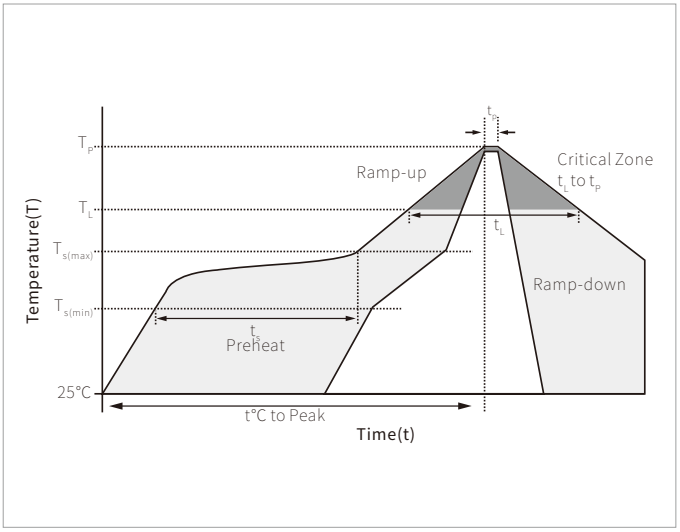
Ref.	mm
A	4.5±0.3mm
B	3.2±0.3mm
C	2.7±0.3mm
D	2.8mm
E	4.0mm
F	5.2mm

SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4-6 seconds

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time(min to max) (t_S)	60 – 150 seconds
Peak Temperature (T_P)		260 °C
Time within 5°C of actual peak Temperature (tp)		20-40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG4532B150A	4.5*3.2*2.7mm	2500PCS	13”

Headquarters
No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline
400-021-5756

Web
Https://www.semiware.com

Sales Center
Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service
Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support
Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions
Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

By QR Code
Website
Wechat

To find your local partner within Semiware' s global network: www.semiware.com